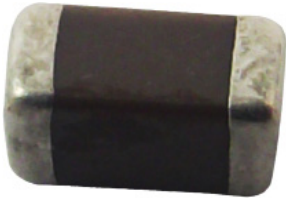


**RoHS
Compliant**



Description:

WTC middle and high voltage series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords increased capacitance values in a given case size and voltage rating.

Chips size 1206 and larger to use on reflow soldering process only. Capacitors with X7R dielectrics are not intended for AC line filtering applications. Capacitors may require protective surface coating to prevent external arcing.

Features:

- High voltage in a given case size.
- High stability and reliability.

Applications:

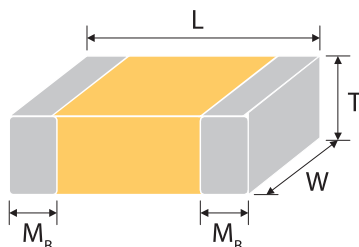
- Snubbers in high frequency power converters.
- High voltage coupling/DC blocking.
- DC-DC converters.
- Back-lighting inverters

How To Order:

MC	1808	N	100	J	202	C	T
	Size	Dielectric	Capacitance	Tolerance	Rated Voltage	Termination	Packaging style
Multicomp	Inch (mm) 0603 (1608) 0805 (2012) 1206 (3216) 1210 (3225) 1808 (4520) 1812 (4532)	N=NP0 (C0G) B=X7R F=Y5V	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5 = 0.5pF 1R0 = 1.0pF 104 = 10x10 ⁰ = 100pF	B = ±0.1pF C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = -20/+80%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 201 = 200V DC 251 = 250V DC 501 = 500V DC 631 = 630V DC 102 = 1000V DC 202 = 2000V DC 302 = V DC	C = Cu/Ni/Sn (for NP0, X7R, Y5V dielectric)	T=7" reeled G=7" reeled

* Partial NP0 items are with Ag/Ni/Sn terminations, please ref to below product range of NP0 dielectric for detail.

External Dimensions:



The outline of MLCC

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol	Remark	M _B (mm)
0603(1608)	1.6±0.1	0.8±0.1	0.8±0.07	S	0.4±0.15
	1.6 +0.15/-0.1	0.8 +0.15/-0.1	0.8 +0.15/-0.1	X	
0805 (2012)	2±0.15	1.25±0.1	0.6±0.1	A	0.6±0.2 (0.5±0.25)*
			0.8 ±0.1	B	
			1.25±0.1	D	

Microwave Multilayer SMD Ceramic Capacitor
0201 to 0805 Sizes (6.3V to 500V), NPO Dielectric, (MCRF)Series



Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		Remark	M _B (mm)
1206 (3216)	3.20±0.15	1.6±0.15	0.80±0.1	B	-	0.5 ±0.2
			0.95±0.1	C	-	
			1.25±0.1	D	#	
	3.20±0.2	1.6±0.2	1.6±0.2	G	#	
1210 (3225)	3.2±0.3	2.5±0.2	0.95±0.1	C	#	0.75±0.25
			1.25±0.1	D	#	
	3.2±0.4	2.5±0.3	1.6±0.2	G	#	
			2.5±0.3	M	#	
1808 (4520)	4.5+0.5/- 0.3	2.03±0.25	1.25±0.1	D	#	0.5±0.25
			2±0.2	K	#	
1812 (4532)	4.5+0.5/- 0.3	3.2±0.3	1.25±0.1	D		0.5±0.25
			1.6±0.2	G		
			2±0.20	K		
		3.2±0.4	2.5±0.3	M		
		3.2±0.4	2.80±0.3	U		

Reflow soldering only is recommended.

General Electrical Data:

Dielectric	NPO	X7R	Y5V
Size	0603, 0805, 1206, 1210, 1808, 1812		0805, 1206, 1210, 1812
Capacitance*	0.5pF to 6800pF		100pF to 1.0µF
Capacitance tolerance***	Cap≤5pF: C (±0.25pF) 5pF<Cap<10pF: D (±0.5pF) Cap≥10pF: F (±1%), G (±2%), J (±5%),K (±10%)		K (±10%), M (±20%) Z (-20/+80%)
Rated voltage (WVDC)	200V to 3kV		200V, 250V
Q/DF*	Cap<30pF: Q≥400+20C Cap≥30pF: Q≥1000	DF≤2.5%	DF≤5%
Insulation resistance at U _r **	U _r =200~630V: ≥10GΩ or R _x C≥100Ω-F whichever is smaller U _r =1000~3000V: ≥10GΩ		
Dielectric strength	200~300V: ≥2 x WVDC 500~999V: ≥1.5 x WVDC 1000~3000V: ≥1.2 x WVDC		
Operating temperature	-55 to +125°C		-25 to +85°C
Capacitance characteristic	±30ppm	±15%	+30/-80%
Termination	Ni/Sn (lead-free termination)		



* Measured at the condition of 30~70% related humidity.

NP0: Apply $1 \pm 0.2V_{rms}$, 1MHz $\pm 10\%$ for Cap $\leq 1,000pF$ and $1 \pm 0.2V_{rms}$, 1kHz $\pm 10\%$ for Cap $> 1,000pF$, 25°C at ambient temperature

X7R, X5R: Apply $1 \pm 0.2V_{rms}$, 1kHz $\pm 10\%$, at 25°C ambient temperature.

Y5V: Apply $1 \pm 0.2V_{rms}$, 1kHz $\pm 10\%$, at 20°C ambient temperature.

** Preconditioning for Class II MLCC: Perform a heat treatment at $150 \pm 10^\circ C$ for 1 hour, then leave in ambient condition for 24 ± 2 hours before measurement.

Size	Thickness/Symbol (mm)		Paper tape		Plastic tape	
			7" reel	13" reel	7" reel	13" reel
0603	0.8 ± 0.07	S	4k	15k	-	-
	$0.8 +0.15/-0.1$	X	4k	15k		
0805	0.6 ± 0.1	A	4k	15k	-	-
	0.8 ± 0.1	B	4k	15k	-	-
	1.25 ± 0.1	D	-	-	3k	10k
1206	0.8 ± 0.1	B	4k	15k	-	-
	0.95 ± 0.1	C	-	-	3k	10k
	1.25 ± 0.1	D	-	-	3k	10k
	1.6 ± 0.2	G	-	-	2k	10k
1210	0.95 ± 0.1	C	-	-	3k	10k
	1.25 ± 0.1	D	-	-	3k	10k
	1.6 ± 0.2	G	-	-	2k	-
	2.5 ± 0.3	M	-	-	1k	6k
1808	1.25 ± 0.1	D	-	-	2k	10k
	2 ± 0.2	K	-	-	1k	6k
1812	1.25 ± 0.1	D	-	-	1k	5k
	1.6 ± 0.2	G	-	-	1k	-
	2 ± 0.2	K	-	-	1k	-

Reliability Test Conditions and Requirements:

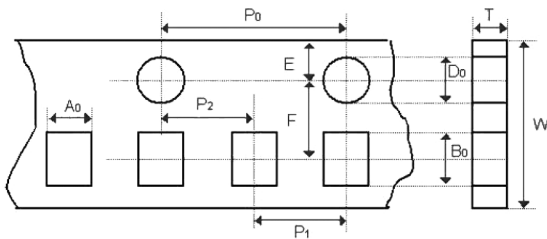
No	Item	Test Condition	Requirements																
1	Visual and Mechanical	-	No remarkable defect. Dimensions to conform to individual specification sheet.																
2	Capacitance	Class I: (NP0) Cap ≤1,000pF, 1 ±0.2Vrms, 1MHz ±10%	Shall not exceed the limits given in the detailed spec.																
3	Q/ D.F. (Dissipation Factor)	Cap >1,000pF, 1 ±0.2Vrms, 1KHz±10% Class II: (X7R, Y5V) 1 ±0.2Vrms, 1kHz ±10%	NP0: Cap ≥30pF, Q ≥1,000; Cap <30pF, Q ≥400 +20C X7R: ≤2.5% Y5V: ≤5%																
4	Dielectric Strength	To apply voltage: 200V~300V ≥2 times V DC 500V~999V ≥1.5 times V DC 1000V~3000V ≥1.2 times V DC Cut-off, set at 10mA TEST = 15 sec. RAMP = 0	No evidence of damage or flash over during test.																
5	Insulation Resistance	Rated voltage: 200~630V	To apply rated voltage (500V max.) for 60 sec. ≥10GΩ or R × C ≥100Ω -F whichever is smaller																
		Rated voltage: ≥630V	To apply 500V for 60 sec. ≥10GΩ																
6	Temperature Coefficient	With no electrical load. <table border="1"> <thead> <tr> <th>T.C.</th> <th>Operating Temp</th> </tr> </thead> <tbody> <tr> <td>NP0</td> <td>-55~125°C at 25°C</td> </tr> <tr> <td>X7R</td> <td>-55~125°C at 25°C</td> </tr> <tr> <td>Y5V</td> <td>-25~85°C at 20°C</td> </tr> </tbody> </table>	T.C.	Operating Temp	NP0	-55~125°C at 25°C	X7R	-55~125°C at 25°C	Y5V	-25~85°C at 20°C	<table border="1"> <thead> <tr> <th>T.C.</th> <th>Capacitance Change</th> </tr> </thead> <tbody> <tr> <td>NP0</td> <td>Within ±30ppm/°C</td> </tr> <tr> <td>X7R</td> <td>Within ±15%</td> </tr> <tr> <td>Y5V</td> <td>Within +30%/-80%</td> </tr> </tbody> </table>	T.C.	Capacitance Change	NP0	Within ±30ppm/°C	X7R	Within ±15%	Y5V	Within +30%/-80%
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T.C.	Capacitance Change																		
NP0	Within ±30ppm/°C																		
X7R	Within ±15%																		
Y5V	Within +30%/-80%																		
7	Adhesive Strength of Termination	Pressurizing force: 5N (≤0603) and 10N (>0603) Test time: 10±1 sec.	No remarkable damage or removal of the terminations.																
8	Vibration Resistance	Vibration frequency: 10~55 Hz/min. Total amplitude: 1.5mm Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) Measurement to be made after keeping at room temp. for 24 ±2 hrs.	No remarkable damage. Cap change and Q/D.F.: To meet initial spec.																
9	Solderability	Solder temperature: 235 ±5°C Dipping time: 2 ±0.5 sec.	95% Min. coverage of all metalized area.																
10.	Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5 ±1 sec. Measurement to be made after keeping at room temp. for 24 ±2 hrs.	No remarkable damage. Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)																

No	Item	Test Condition	Requirements															
11	Resistance to Soldering Heat	Solder temperature: 260 ±5°C Dipping time: 10 ±1 sec Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder. Before initial measurement (Class II only): Perform 150 +0/-10°C for 1 hr and then set for 24 ±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24 ±2 hrs.	No remarkable damage. Cap change: NPO: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements. 25% Max. leaching on each edge.															
12	Temperature Cycle	Conduct the five cycles according to the temperatures and time. <table border="1" data-bbox="363 772 790 974"> <thead> <tr> <th>Step</th> <th>Temp. (°C)</th> <th>Time (min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>Min. operating temp. +0/-3</td> <td>30 ±3</td> </tr> <tr> <td>2</td> <td>Room temp.</td> <td>2~3</td> </tr> <tr> <td>3</td> <td>Max. operating temp. +3/-0</td> <td>30 ±3</td> </tr> <tr> <td>4</td> <td>Room temp.</td> <td>2~3</td> </tr> </tbody> </table> Before initial measurement (Class II only): Perform 150 +0/-10°C for 1 hr and then set for 24 ±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24 ±2 hrs.	Step	Temp. (°C)	Time (min.)	1	Min. operating temp. +0/-3	30 ±3	2	Room temp.	2~3	3	Max. operating temp. +3/-0	30 ±3	4	Room temp.	2~3	No remarkable damage. Cap change: NPO: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements.
Step	Temp. (°C)	Time (min.)																
1	Min. operating temp. +0/-3	30 ±3																
2	Room temp.	2~3																
3	Max. operating temp. +3/-0	30 ±3																
4	Room temp.	2~3																
13	Humidity (Damp Heat) Steady State	Test temp.: 40±2°C Humidity: 90% ~ 95% RH Test time: 500+24/-0hrs. Before initial measurement (Class II only): Perform 150 +0/-10°C for 1 hr and then set for 24 ±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24 ±2 hrs.	No remarkable damage. Cap change: NPO: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% Q/D.F. value: NPO: Cap ≥30pF, Q ≥350; 10pF ≤Cap <30pF, Q ≥275 +2.5C Cap <10pF; Q ≥200 +10C X7R: ≤3.0% Y5V: ≤7.5% I.R.: ≥1GΩ or R × C ≥50Ω -F whichever is smaller.															
14	Humidity (Damp Heat) Load	Test temp.: 40 ±2°C Humidity: 90% ~ 95%RH Test time: 500 +24/-0 hrs. To apply voltage: rated voltage (Max. 500V) Before initial measurement (Class II only): To apply test voltage for 1hr at 40°C and then set for 24 ±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24 ±2 hrs.	No remarkable damage. Cap change: NPO: within ±7.5% or ±0.75pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% Q/D.F. value: NPO: Cap ≥30pF, Q ≥200; Cap <30pF, Q ≥100 +10/3C X7R: ≤3.0% Y5V: ≤7.5% I.R.: ≥500MΩ or R × C ≥25Ω-F whichever is smaller.															

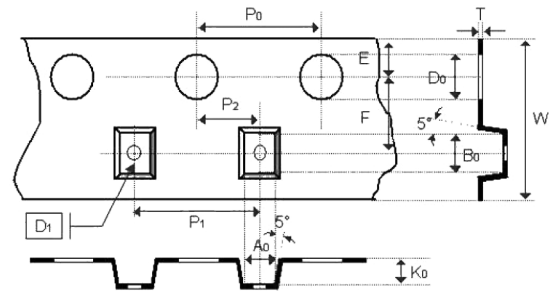
No	Item	Test Condition	Requirements
15	High Temperature Load (Endurance)	Test temp.: NPO, X7R: 125±3°C Y5V: 85±3°C To apply voltage: (1) <500V: 200% of rated voltage. (2) 500V: 150% of rated voltage. (3) ≥630V: 120% of rated voltage. (4) 1206,NPO ≥1.5pF: 100% of rated voltage. Test time: 1,000 +24/-0 hrs. Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24 ±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs	No remarkable damage. Cap change: NPO: within ±3.0% or ±0.3pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% Q/D.F. value: NPO: Cap ≥30pF, Q ≥350 10pF ≤Cap <30pF, Q ≥275 +2.5C Cap <10pF, Q ≥200 +10C X7R: ≤3.0% Y5V: ≤7.5% I.R.: ≥1GΩ or R × C ≥50Ω -F whichever is smaller.

Appendixes

Tape & Reel Dimensions

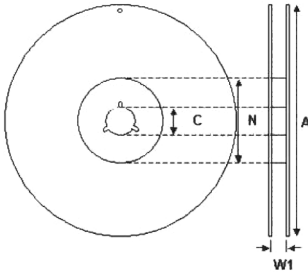


The dimension of paper tape



The dimension of plastic tape

Size	0603		0805		1206		1210		1808		1812
Thickness	S, X	B	C, D, I	B	C, D	G	C, D, G	M	D	K	D, K
A ₀	1.02 ±0.05	1.5 ±0.1	< 1.57	2 ±0.1	<1.85	<1.95	<2.97	<2.97	<2.35	<2.35	<3.81
B ₀	1.8 ±0.05	2.3 ±0.1	< 2.4	3.5 ±0.1	<3.46	<3.67	<3.73	<3.73	<4.98	<5	<5.3
T	0.95 ±0.05	0.95 ±0.05	0.23 ±0.05	0.95 ±0.05	0.23 ±0.05	0.23 ±0.05	0.23 ±0.05	0.23 ±0.05	0.25 ±0.05	0.25 ±0.05	0.25 ±0.05
K ₀	-	-	<2.5	-	<2.5	<2.5	<2.5	<3	<2.5	<2.5	<2.5
W	8 ±0.1	8 ±0.1	8 ±0.1	8 ±0.1	8 ±0.1	8 ±0.1	8 ±0.1	8 ±0.1	12 ±0.2	12 ±0.2	12 ±0.2
P ₀	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1
10 × P ₀	40 ±0.1	40.0 ±0.1	40 ±0.1	40 ±0.1	40 ±0.1	40 ±0.1	40 ±0.1	40 ±0.1	40 ±0.1	40 ±0.1	40 ±0.1
P ₁	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	8 ±0.1
P ₂	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05
D ₀	1.55 ±0.05	1.55 ±0.05	1.5 ±0.05	1.5 ±0.05	1.5 ±0.05	1.5 ±0.05	1.5 ±0.05	1.5 ±0.05	1.5 ±0.05	1.5 ±0.05	1.5 ±0.05
D ₁	-	-	1 ±0.1	-	1 ±0.1	1 ±0.1	1 ±0.1	1 ±0.1	1.5 ±0.1	1.5 ±0.1	1.5 ±0.1
E	1.75 ±0.05	1.75 ±0.05	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1
F	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	5.5 ±0.05	5.5 ±0.05	5.5 ±0.05

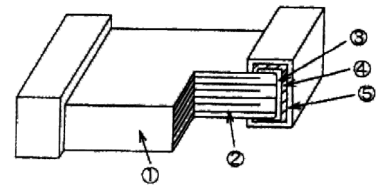


The dimension of reel

Size	0603, 0805, 1206, 1210		1808, 1812	
Reel size	7"	10"	13"	7"
C	13 +0.5/-0.2	13 +0.5/-0.2	13 +0.5/-0.2	13 +0.5/-0.2
W ₁	8.4 +1.5/-0	8.4 +1.5/-0	8.4 +1.5/-0	12.4 +2/-0
A	178 ±0.1	250 ±1	330 ±1	178 ±0.1
N	60 +1/-	100 ±1	100 ±1	60.5 ±1

Constructions:

No.	Name	NP0	NPO, X7R, Y5V
1	Ceramic material	BaTiO ₃ based	
2	Inner electrode	AgPd alloy	Ni
3	Termination	Inner layer	Ag
4		Middle layer	Ni
5		Outer layer	Sn



The construction of MLCC

* Partial NP0 items are with Ag/Ni/Sn(NME) terminations, please ref to product range for detail.

Storage and handling conditions

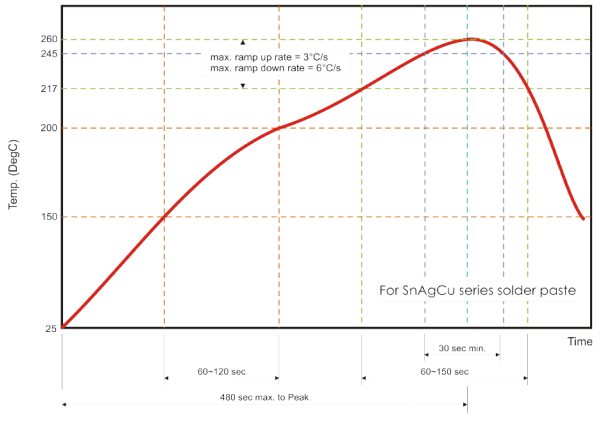
- (1) To store products at 5 to 40 C ambient temperature and 20 to 70% related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

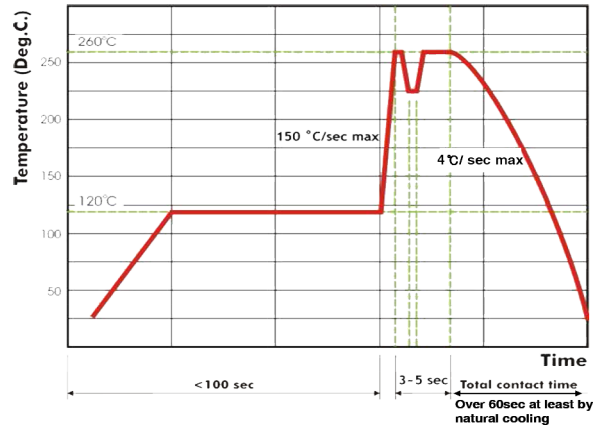
- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended Soldering Conditions:

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.



Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.



Recommended wave soldering profile for SMT process with SnAgCu series solder.

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